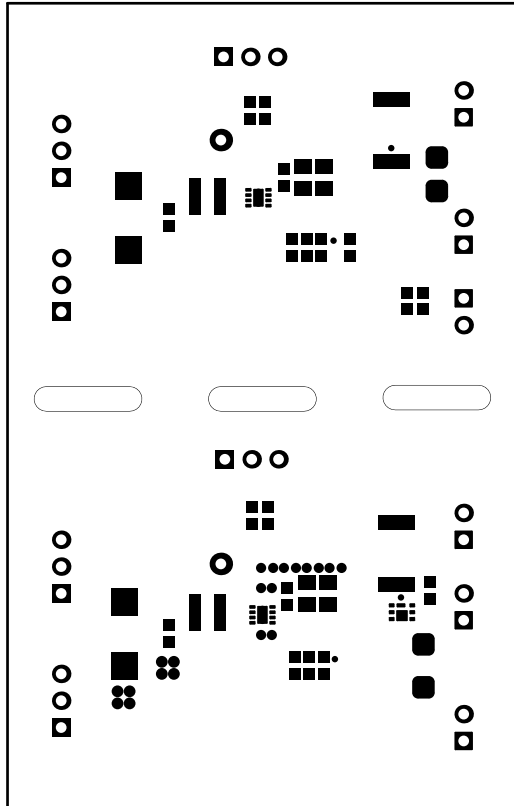
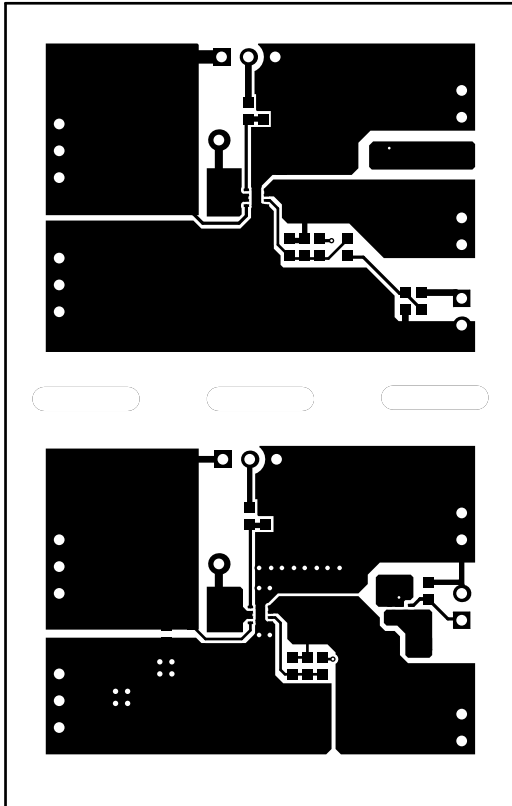


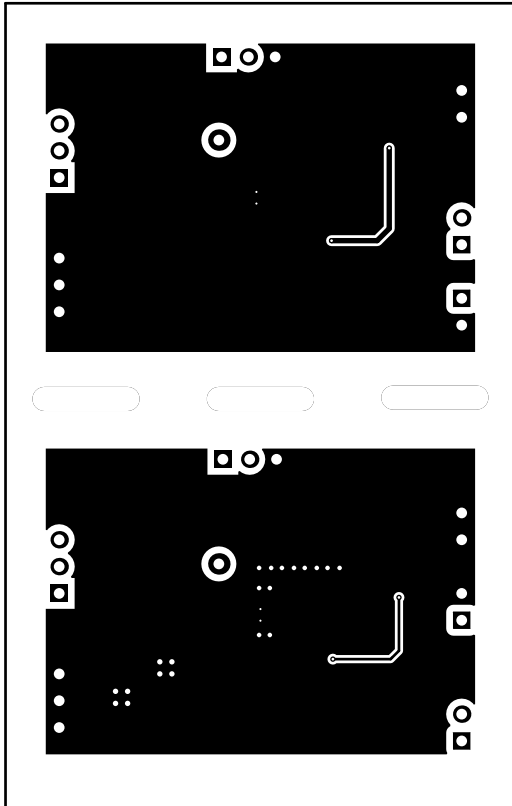
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	PMP15037	REV:	E1	SUN REV:	Not In VersionControl
LAYER NAME =	Top Overlay	TID #:	N/A			
PLOT NAME =	Top Overlay	GENERATED :	9/21/2017	5:14:39 PM	TEXAS INSTRUMENTS	



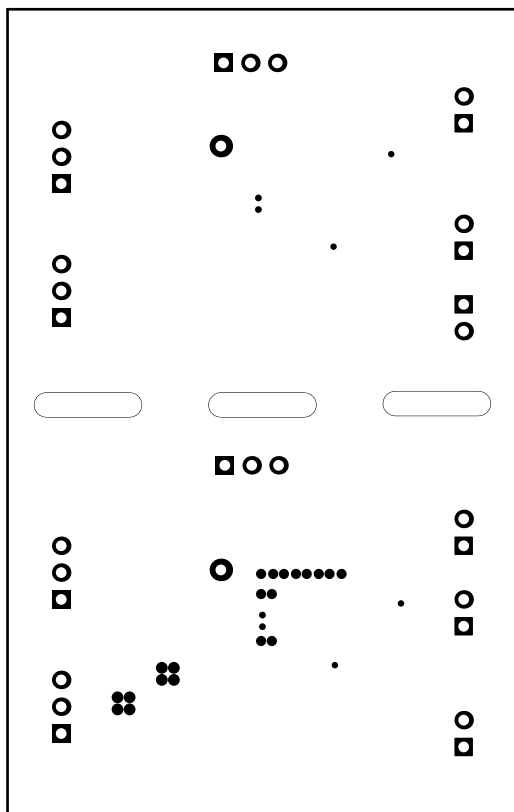
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15037	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 9/21/2017	5:14:40 PM	TEXAS INSTRUMENTS



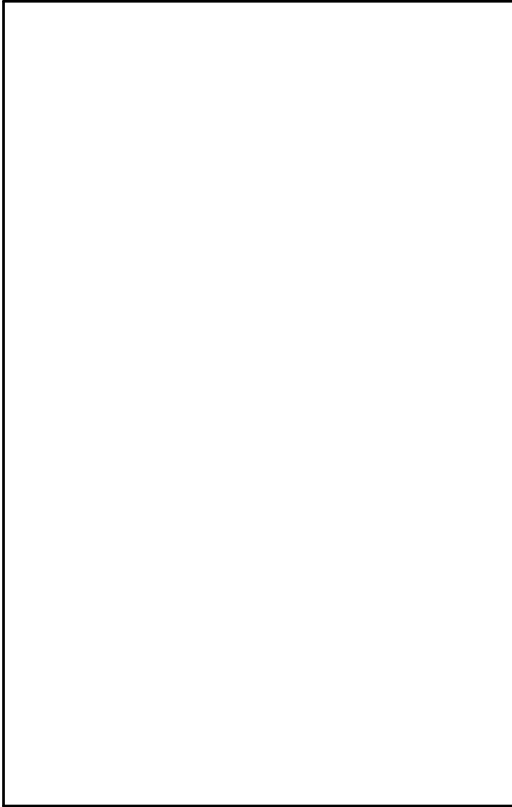
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15037	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 9/21/2017	5:14:41 PM	TEXAS INSTRUMENTS



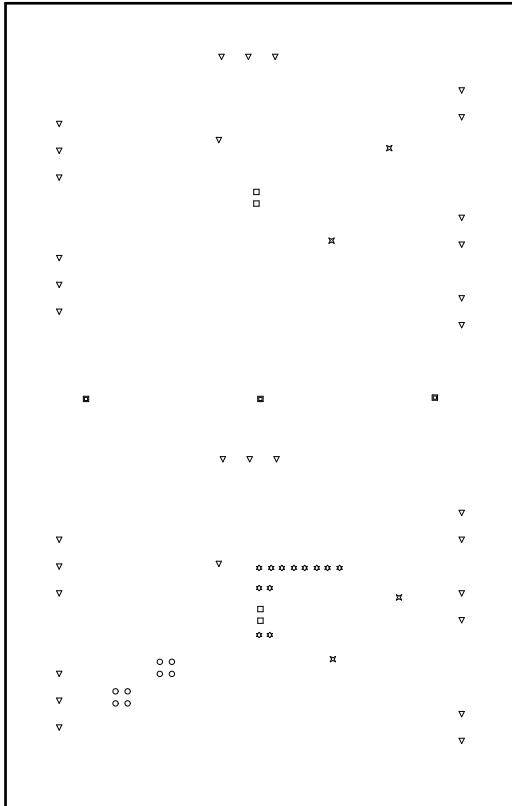
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	PMP15037	REV:	E1	SUN REV:	Not In VersionControl
LAYER NAME =	Bottom Layer	TID #:	N/A			
PLOT NAME =	Bottom Layer	GENERATED :	9/21/2017	5:14:43 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15037	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 9/21/2017	5:14:44 PM	TEXAS INSTRUMENTS



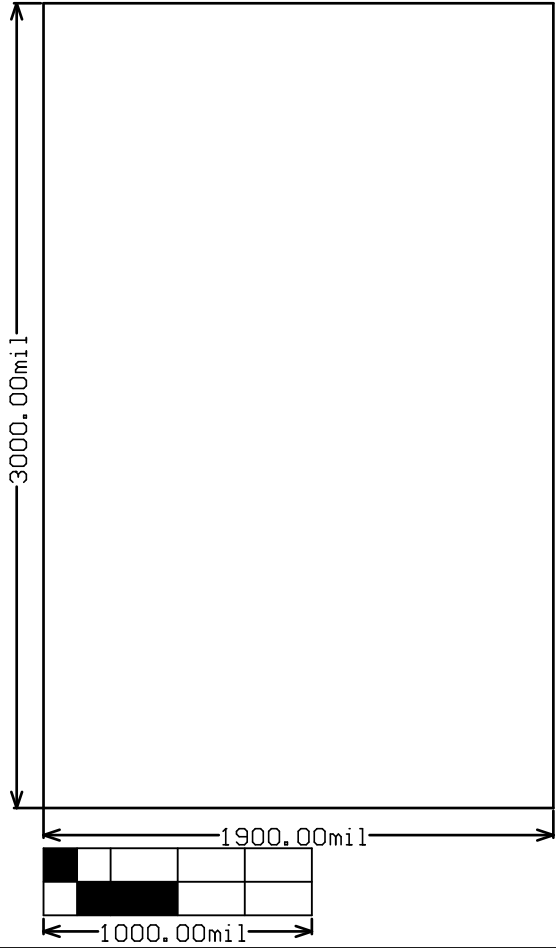
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15037	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 9/21/2017	5:14:45 PM	TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
□	4	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
✕	4	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
✳	12	17.00mil (0.432mm)	PTH	Round	Top Layer - Bottom Layer	
○	8	20.00mil (0.508mm)	PTH	Round	Top Layer - Bottom Layer	
▽	32	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
■	3	90.00mil (2.286mm)	PTH	Slot	Top Layer - Bottom Layer	
53 Total						

Slot definitions: Routed Path Length = Calculated from tool start centre position to tool end centre position.  
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	PMP15037	REV:	E1	SUN REV:	Not In VersionControl
LAYER NAME =	Drill Drawing	TID #:	N/A			
PLOT NAME =	Drill Drawing	GENERATED :	9/21/2017	5:14:46 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	PMP15037	REV:	E1	SUN REV:	Not In VersionControl
LAYER NAME =	M2 Board Dimensions	TID #:	N/A			
PLOT NAME =	Board Dimensions	GENERATED :	9/21/2017	5:14:47 PM	TEXAS INSTRUMENTS	



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